

ST02-36G1

TVS
4.0A, 200W

Feature

- Peak pulse power:200W
- Ultra-small SMD
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): G1F
Package (JEDEC Code): DO-219AB similar
Package (JEITA Code): SC-109



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | Unit |
|-------------------------------------|--------------------|---|------------|------|
| Storage temperature | Tstg | | -55 to 175 | °C |
| Operating junction temperature | Tj | | -55 to 175 | °C |
| Maximum surge reverse current | I _{RSM} | 10/1000μs, Non-repetitive, Exponential wave ※ | 4 | A |
| Maximum surge reverse power | P _{RSM} | 10/1000μs, Non-repetitive ※ | 200 | W |
| Continuous (direct) reverse voltage | V _{R(DC)} | | 27 | V |

※ :See the original Specifications

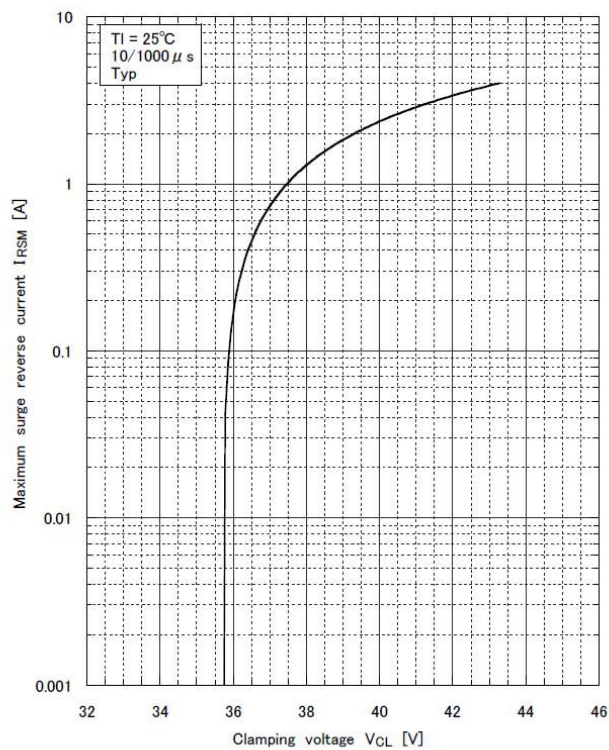
Electrical Characteristics (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | | | Unit |
|--------------------|-----------------|---|---------|-----|-----|------|
| | | | MIN | TYP | MAX | |
| Breakdown voltage | V _{BR} | IR=2mA, Pulse measurement | 34 | 36 | 38 | V |
| Reverse current | I _R | VR=27V, Pulse measurement | | | 5 | μA |
| Thermal resistance | Rth(j-l) | Junction to lead, On glass-epoxy substrate ※ | | | 20 | °C/W |
| Thermal resistance | Rth(j-a) | Junction to ambient, On glass-epoxy substrate ※ | | | 120 | °C/W |

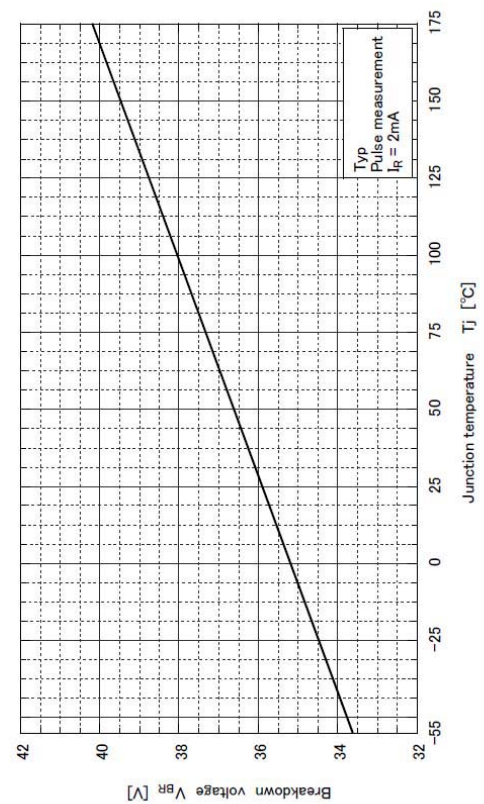
※ :See the original Specifications

CHARACTERISTIC DIAGRAMS

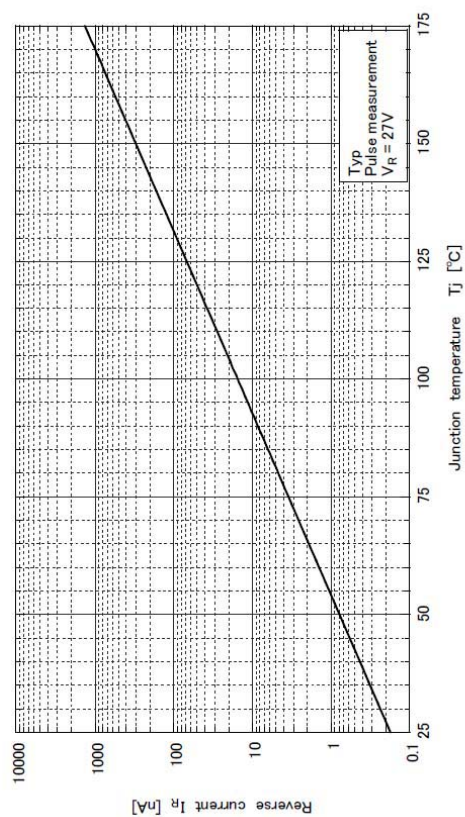
Maximum surge reverse current vs Clamping voltage



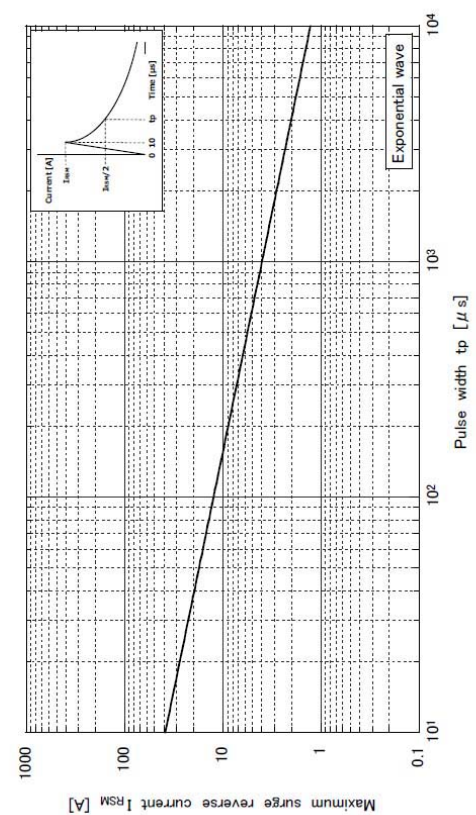
Breakdown voltage vs Junction temperature



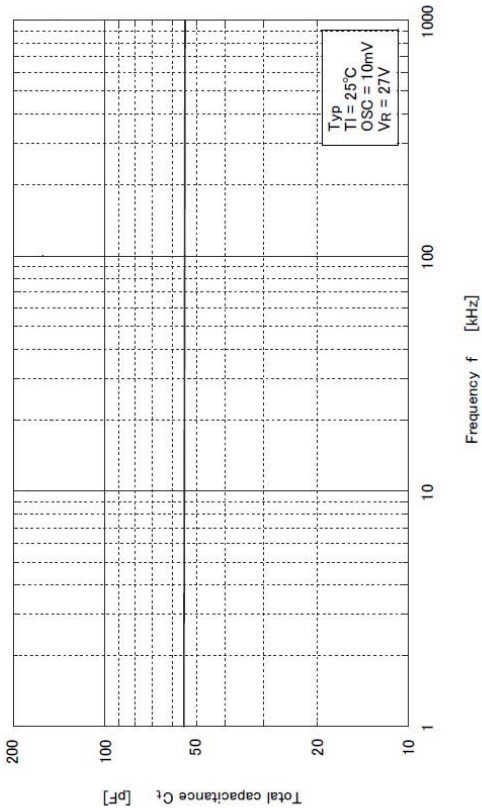
Reverse current vs Junction temperature



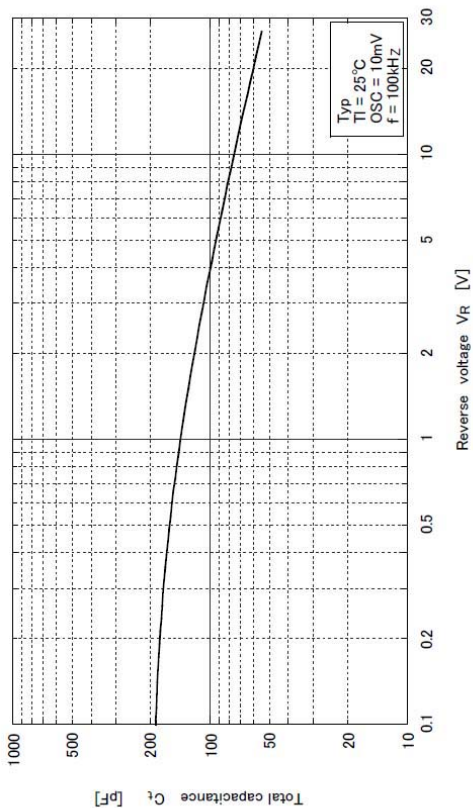
Maximum surge reverse current vs Pulse width



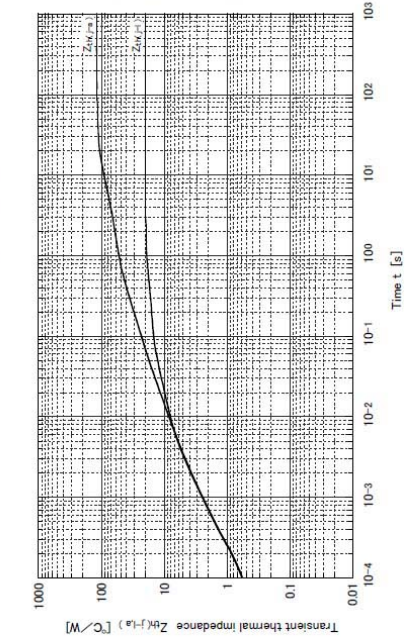
Total capacitance vs Frequency



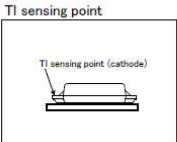
Total capacitance vs Reverse voltage



Transient thermal impedance vs Time

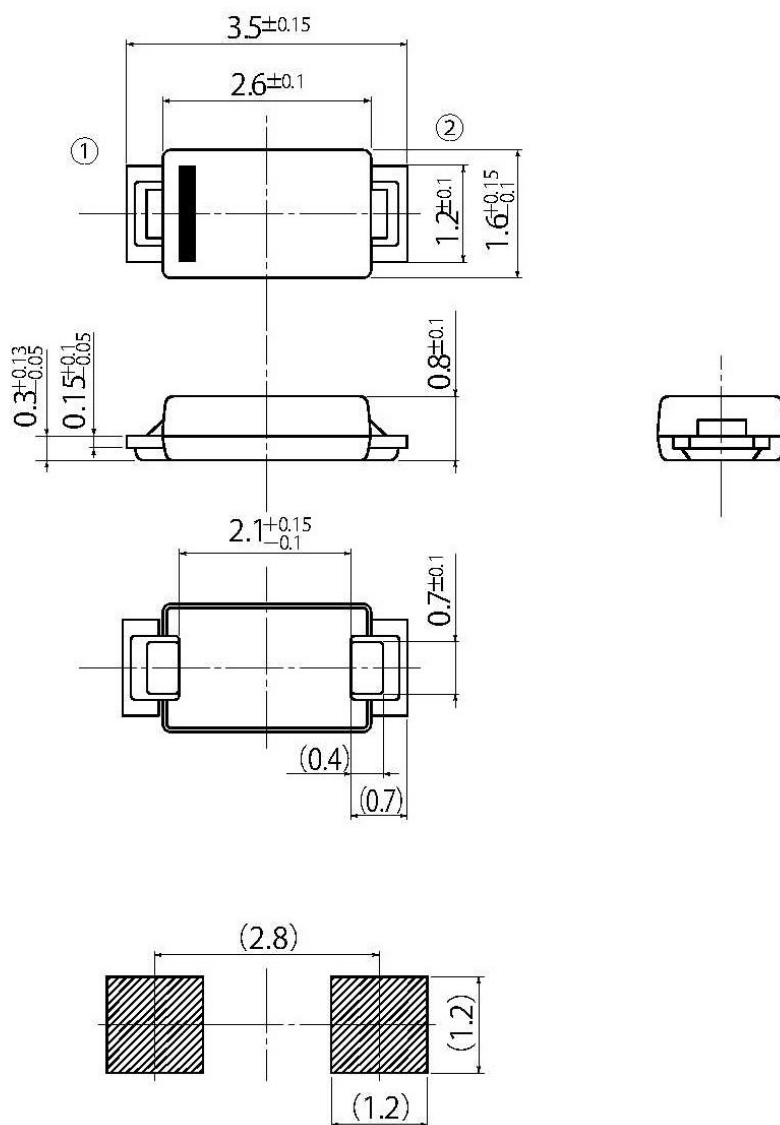


| Substrate detail | |
|---------------------|---------------------|
| Type | Glass-epoxy |
| Size | 1 inch ² |
| Thickness | 1mm |
| Conductor thickness | 35 μm |
| Pattern area | 160mm ² |



B1

| | |
|------------|------------------|
| JEDEC Code | DO-219AB similar |
| JEITA Code | SC-109 |
| House Name | G1F |



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

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